

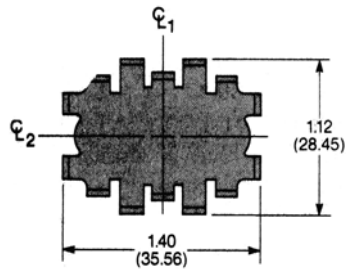
METAL CASE, CASE-MOUNTED SEMICONDUCTORS

Part Number Series LB66B1

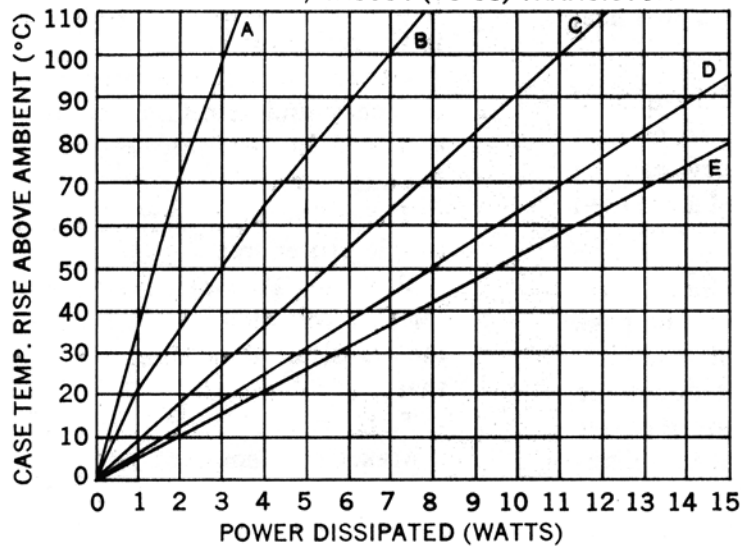
Natural Conv. (°C/W): 17.1

Forced Air (°C/W): 5.3

Mounting Envelope: 1.40" x 1.12" x .50"



LB66B1CB w/2N3054 (TO-66) TRANSISTOR



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

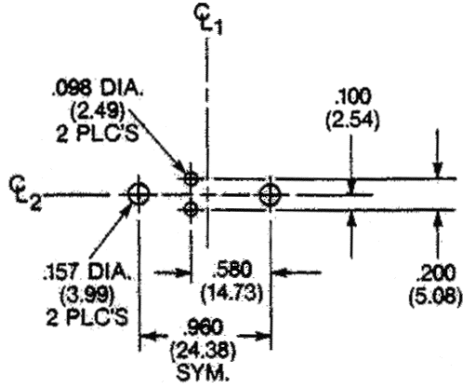
- Thermal Resistance Case to Sink is 0.5-0.7 °C/W w/Joint Compound.
- Derate 1.4 °C/watt for unplated part in natural convection only.

Ordering Information

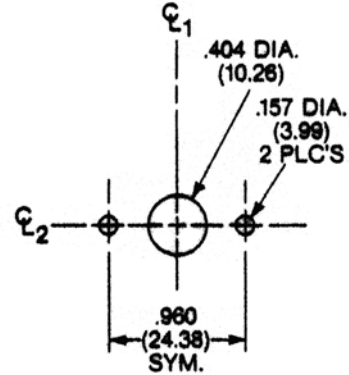
CTS IERC PART NO.			Semiconductor Accommodated	Hole patt. ref. no.	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
LB66B1-76U	LB66B1-76CB	LB66B1-76B	Undrilled	--	6.2
LB66B1U	LB66B1CB	LB66B1B	TO-66	9	6.2
LB66B1-67U	LB66B1-67CB	LB66B1-67B	TO-66 IC	7	6.2
LB66B1-77U	LB66B1-77CB	LB66B1-77B	TO-66 IC (Socket)	10	6.2

HOLE PATTERNS

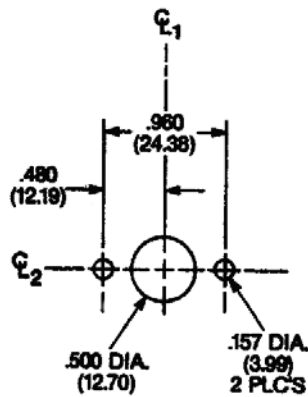
9. Hole Pattern no. 133 accommodates TO-66s. Available in LB series heat dissipators only.



7. Hole pattern no. 191 accommodates To-66 Ics. Available in LA-A, LA-B, and LB series heat dissipators only.



10. Hole pattern no. 225 accommodates TO-66 ICs (socket). Available in LB series heat dissipators only.



CTS IERC, Heat Sinks and Thermal Management Solutions

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